

Title (en)

METHOD FOR PRODUCING A PARTIALLY SHAPED ELECTRICALLY CONDUCTIVE STRUCTURE AND MULTILAYER COMPRISING SUCH A STRUCTURE

Title (de)

VERFAHREN ZUR ERZEUGUNG EINER PARTIELL AUSGEFORMTEN ELEKTRISCH LEITFÄHIGEN STRUKTUR UND MEHRSCHICHTKÖRPER UMFASSEND EINER SOLCHEN STRUKTUR

Title (fr)

PROCEDE DE FABRICATION D'UNE STRUCTURE CONDUCTRICE PARTIELLEMENT DEMOULEE ET SUBSTRAT MULTICOUCHES COMPRENANT UNE TELLE STRUCTURE

Publication

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Application

EP 06791504 A 20060426

Priority

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Abstract (en)

[origin: DE102005019920A1] The method involves producing a latent magnetic image of a graphic form of an electro conductive structure from a digital data set on a magnetizable printing drum (11), where the data set defines the graphic form of the structure, and the latent magnetic image is formed of magnetic and unmagnetic pixels. Magnetic particles with electro conductive upper surface are energized by the magnetic pixels using the printing drum, and the structure is arranged on a carrier foil (16) by the latent magnetic image to the graphic form. The structure is fixed on the foil. An independent claim is also included for a multi-layered body comprising a partially formed electroconductive structure.

IPC 8 full level

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CPC (source: EP US)

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Citation (search report)

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